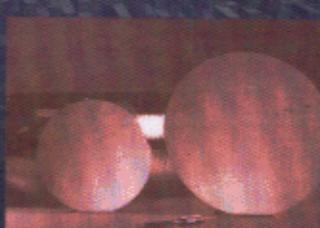


# *MEMS & MICROSYSTEMS*

## *Design and Manufacture*

Tai-Ran Hsu



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